502505945 09/23/2013

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mou-Shiung Lin	12/16/2009
Jin-Yuan Lee	12/18/2009

RECEIVING PARTY DATA

Name:	MEGICA CORPORATION	
Street Address:	8F1, NO. 9, PUDING ROAD, EAST DISTRICT	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	30072	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14034440

CORRESPONDENCE DATA

Fax Number: 3102015219

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 310 277 7200

Email: qualcomm-uspto@seyfarth.com

Correspondent Name: Seyfarth Shaw LLP

Address Line 1: 2029 Century Park East, Suite 3500
Address Line 4: Los Angeles, CALIFORNIA 90067-3021

ATTORNEY DOCKET NUMBER:	093045D1
NAME OF SUBMITTER:	Joseph Lutz
Signature:	/Joseph Lutz/
Date:	09/23/2013

Total Attachments: 1

source=093045D1-Assignment#page1.tif

CH \$40.0

PATENT REEL: 031261 FRAME: 0805 Docket No.: 085027-0666

ASSIGNMENT

WHEREAS We, Mou-Shiung Lin and Jin-Yuan Lee of 28 Ginsan 10th Street, Hsin-Chu, 300, Taiwain, and No. 11, Lane 4, An-Ho Street, Hsin-Chu 300, Taiwain, respectively, have made a certain new and useful invention as set forth in an application for United States Letters Patent, entitled CHIP PACKAGES WITH POWER MANAGEMENT INTEGRATED CIRCUITS AND RELATED TECHNIQUES, and filed concurrently herewith;

AND WHEREAS, Megica Corporation, a corporation of Taiwan and having an address of 8F.-1. No. 29, Puding Road, East District, Hsin-Chu 30072, Taiwan (R.O.C.) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any and all Letters Patent of the United States and foreign countries which may be obtained therefor:

NOW, THEREFORE, for good and valuable consideration, the receipt for and sufficiency of which is hereby acknowledged, We do hereby sell, assign, transfer and set over unto Megica Corporation, its legal representatives, successors, and assigns, the entire right, title and interest in and to said invention as set forth in the above-mentioned application, including the right of priority and including any continuations, continuations-in-part, divisions, reissues, re-examinations or extensions thereof, and in and to any and all patents of the United States and foreign countries which may be issued for said invention;

UPON SAID CONSIDERATIONS, We hereby agree with the said assignee that We will not execute any writing or do any act whatsoever conflicting with these presents, and that We will, at any time upon request, without further or additional consideration but at the expense of said assignee, execute such additional assignments and other writings and do such additional acts as said assignee may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuations, continuations-in-part, reexamined, reissued, or extended Letters Patent of the United States or of any and all foreign countries on said invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of the assigns and legal representatives of assignor and assignee;

AND We request the Commissioner for Patents and Trademarks to issue any Letters Patent of the United States which may be issued for said invention to said Megica Corporation, its legal representatives, successors or assigns, as the sole owner of the entire right, title and interest in and to said patent and the invention covered thereby.

SDO 181642-1.085027.9666

Date

PATENT REEL: 031261 FRAME: 0806

RECORDED: 09/23/2013